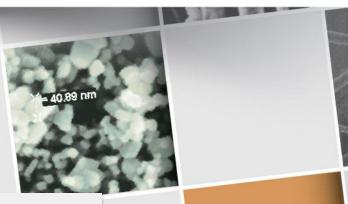




Catching the Nanotechnology Wave: **Needs, Risks, and Opportunities**

November 1, 2013

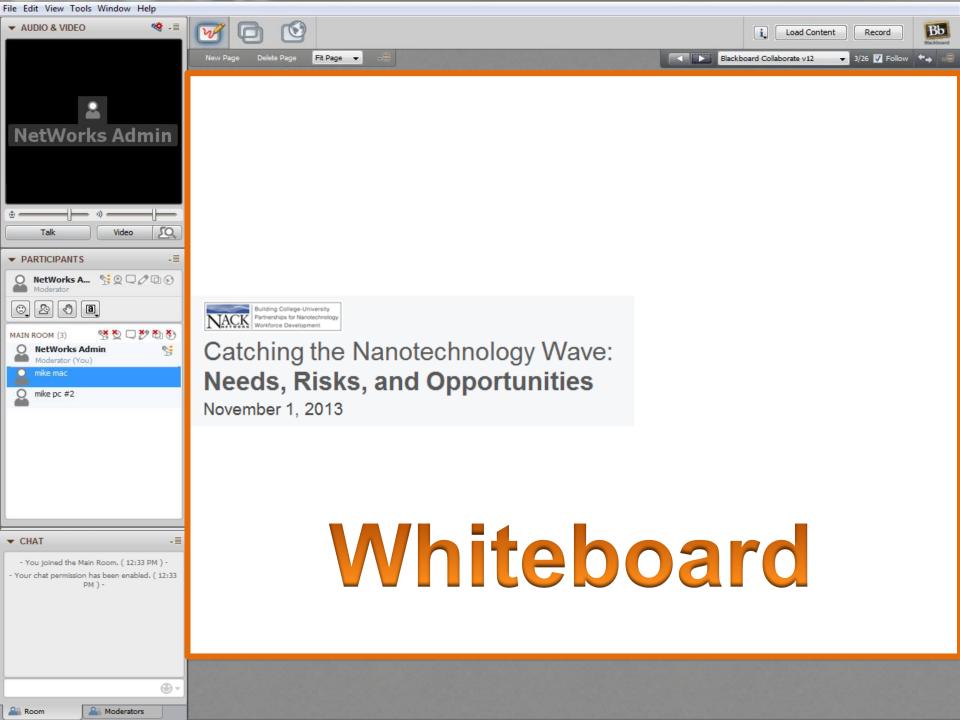
The webinar will begin at 1pm Eastern Time

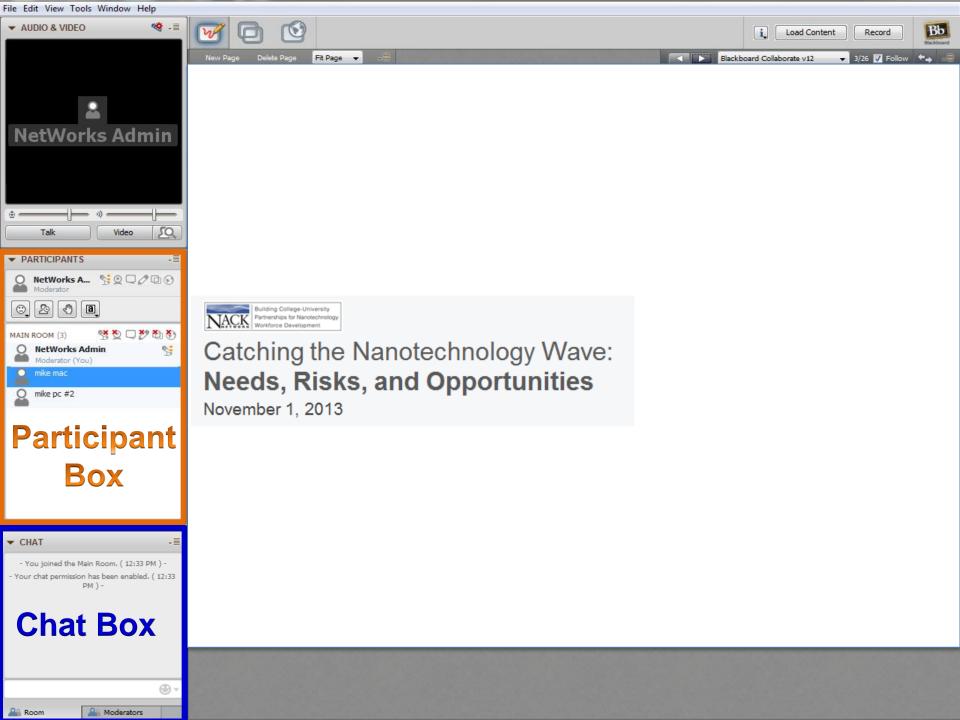


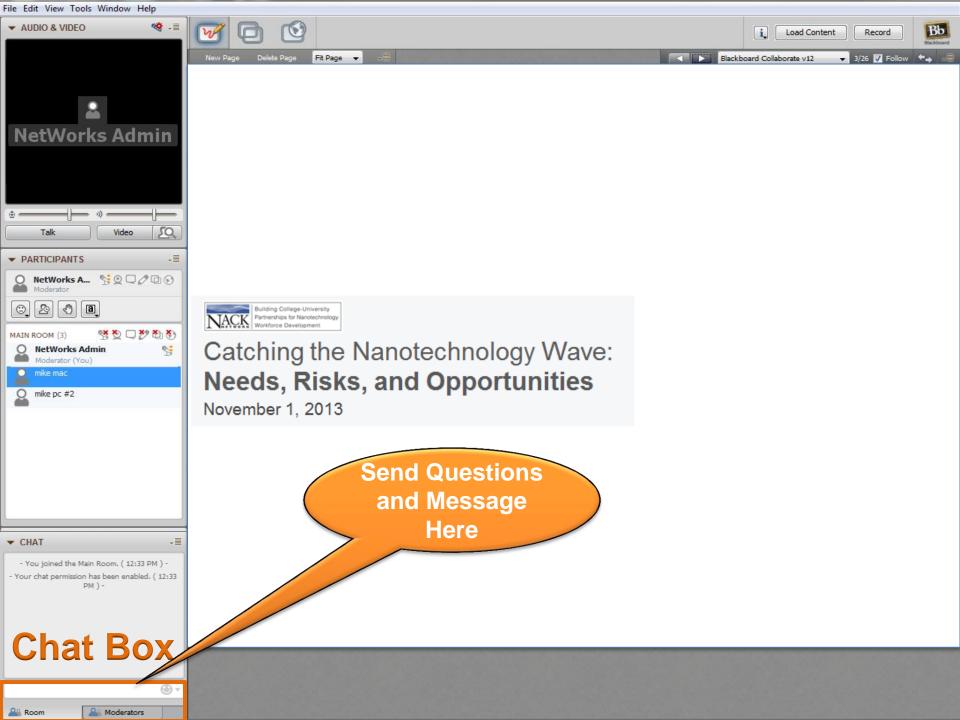
= 114.1 nm

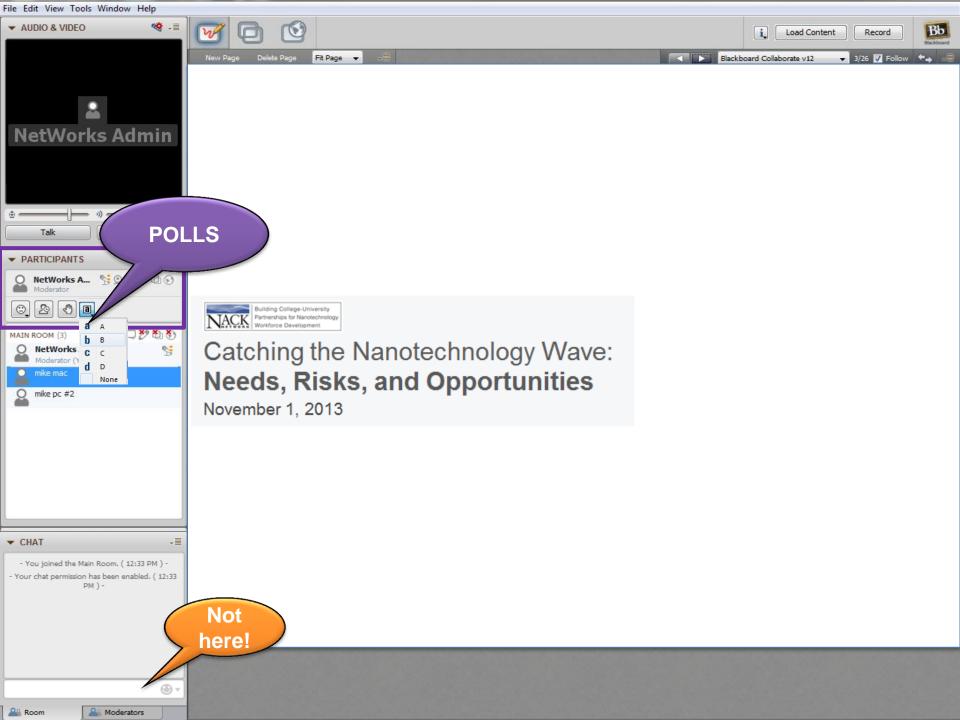
= 322.6 nm

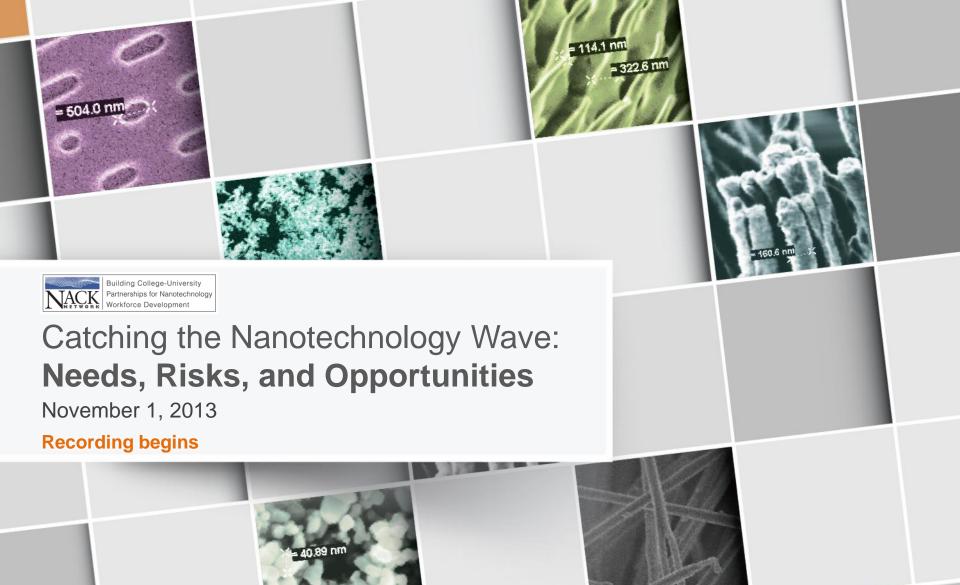
Perform an audio check by going to Tools > Audio > Audio Setup Wizard













Brought to You By:

The NACK Network established at the Pennsylvania State College of Engineering, and funded in part by a grant from the National Science Foundation (DUE 1205105).





Catching the Nanotechnology Wave:

Needs, Risks, and Opportunities

Presented by MATEC NetWorks

November 1, 2013

Presenter



Daniel J. C. Herr

Professor and Nanoscience Department Chair and Director - Nanomanufacturing Innovation Consortium, The Joint School of Nanoscience and Nanoengineering

Co-Chair – Emerging Research Materials Working Group International Technology Roadmap for Semiconductors

djherr@uncg.edu / 336-285-2862

Host: Michael Lesiecki



Audience Poll

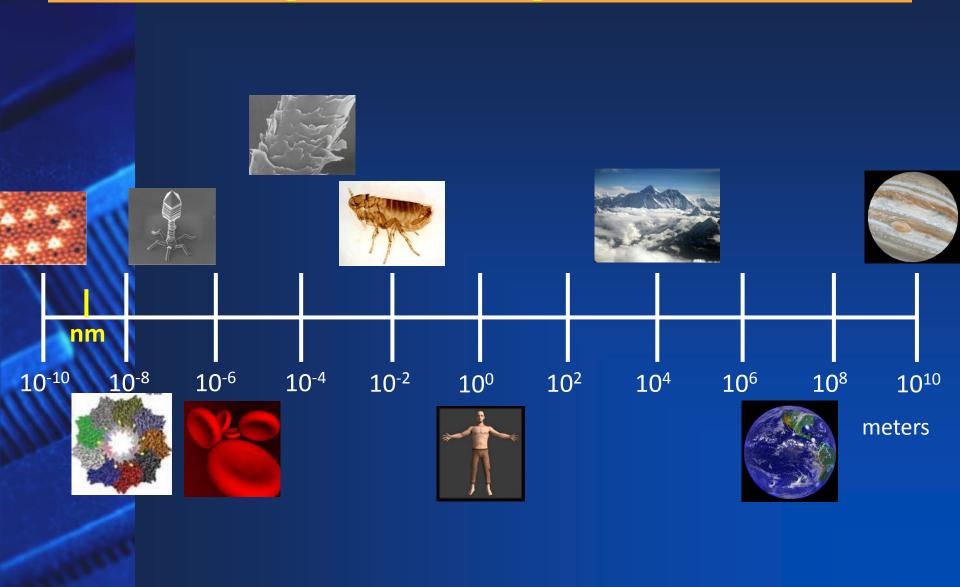
Who Are You?

- A. K-12 Educator
- B. Community College Educator
- C. 4-year College/University Educator/Researcher
- D. Industry scientist, engineer or technologist
- E. Interested member of the community

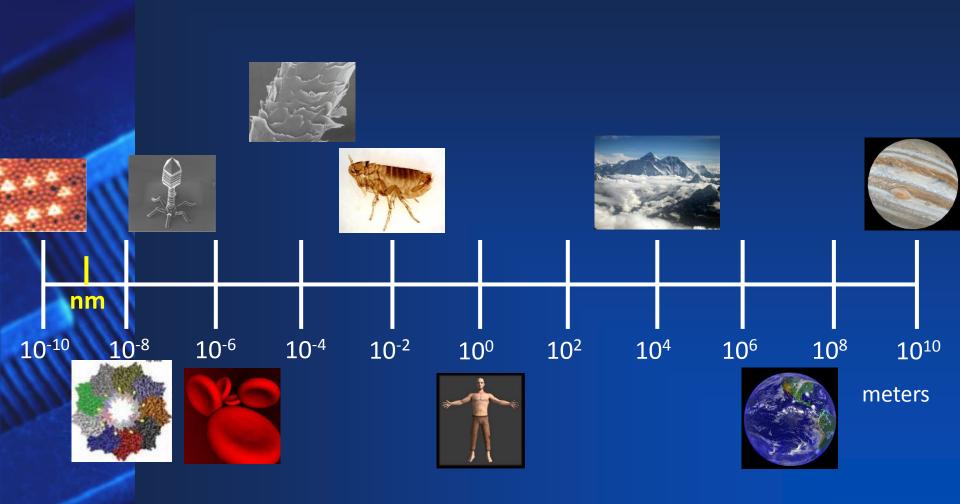
Overview

- What's the big deal about nanotechnology?
- Current device trends and challenges
- What can we learn from Nature?
- □ Emerging high-impact opportunities
- Inspiring the next generation of innovators

What's the Big Deal About Nanotechnology: Orders of Magnitude in Length

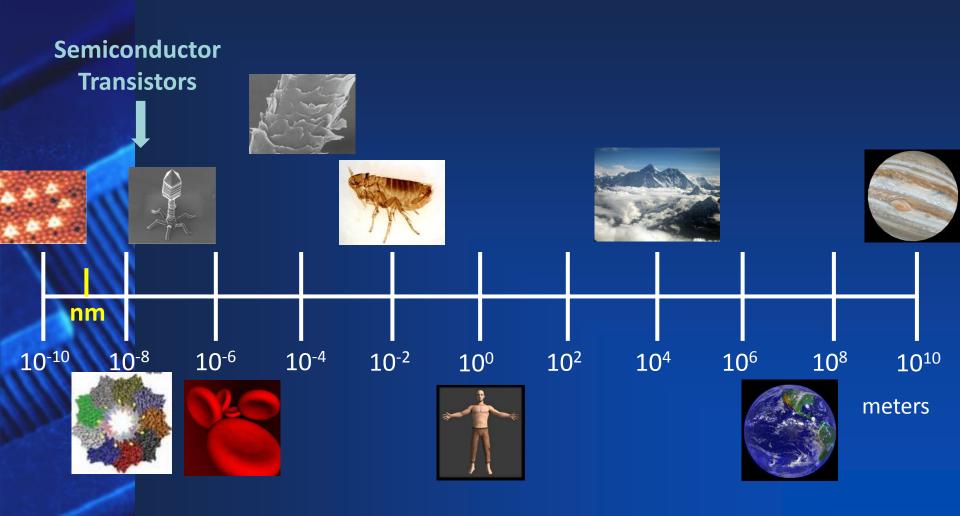


What's the Big Deal About Nanotechnology: Orders of Magnitude in Length



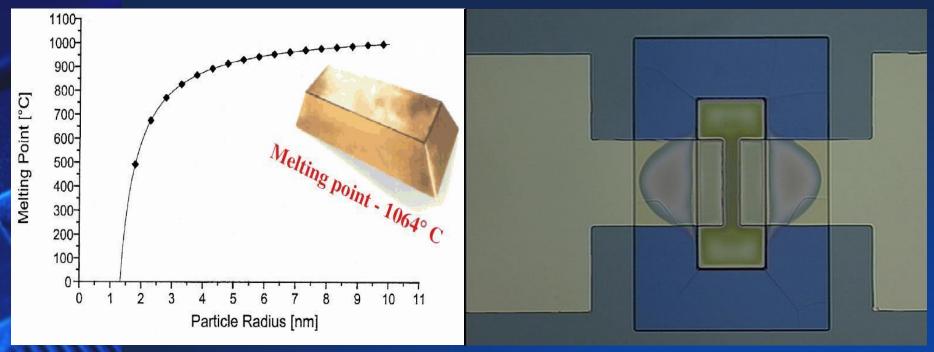
We are closer in size to Mount Everest than we are to a protein.

What's the Big Deal About Nanotechnology: Orders of Magnitude in Length



We are closer in size to Mount Everest than we are to a protein.

Benefit Unusual Properties Emerge at the Nanoscale: Ex. Metal Nanoparticles as Pb Solder Replacements

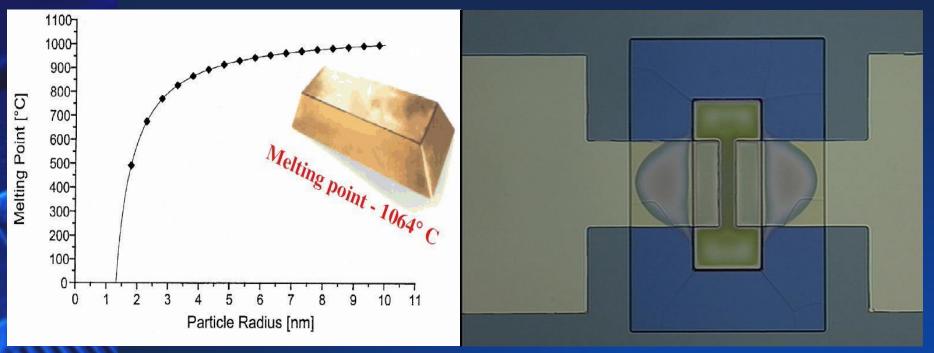


K. J. Klabunde, "Nanoscale Materials in Chemistry", Wiley/Interscience publishers, New York (2001).

D. Huang, F. Liao, S. Molesa, D. Redinger, and V. Subramanian, *J. Electrochemical Soc.*, 150, G412-G417 (2003).

Ex. Droplet on Demand patterning of organically coated Cu nanoparticles enables low temperature [130 C] sintering, enhanced conductivity, i.e. better than lead.

Benefit Unusual Properties Emerge at the Nanoscale: Ex. Metal Nanoparticles as Pb Solder Replacements



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Ex. Droplet on Demand patterning of organically coated Cu nanoparticles enables low temperature [130 C] sintering, enhanced conductivity, i.e. better than lead.

What is the ESH impact of organically coated 3 nm Cu particles?

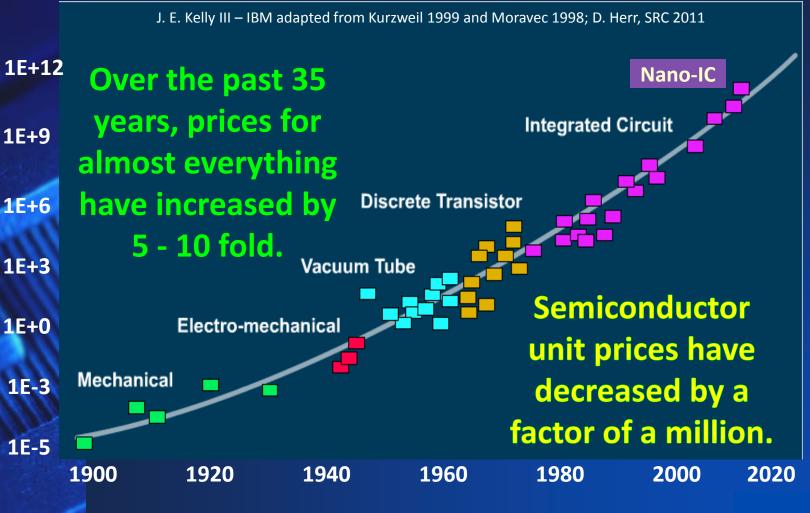
Scaling: The Benefits and the Costs - Ex. Moore's 1st Law [Benefits]

Over the past 35 years, prices for almost everything have increased by 5 - 10 fold.

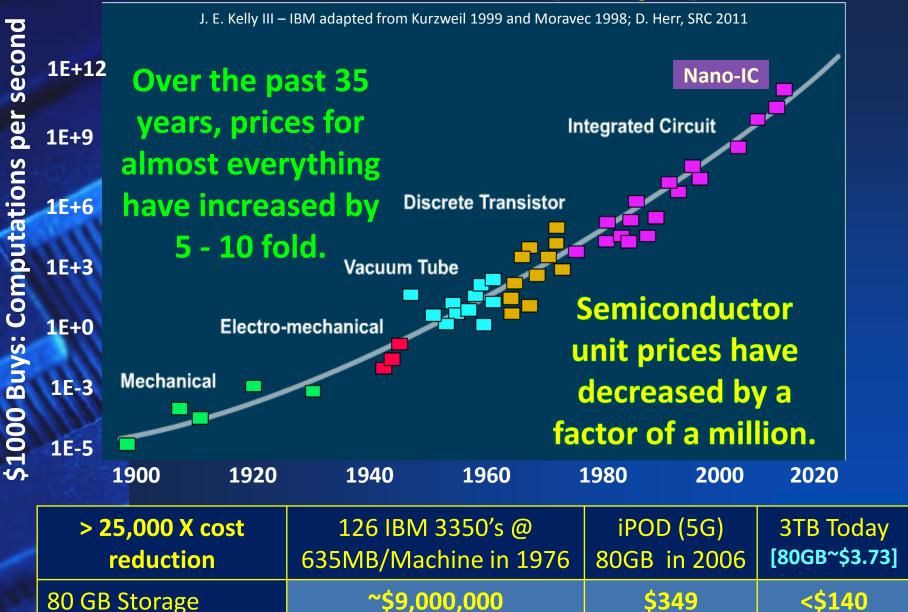
Scaling: The Benefits and the Costs - Ex. Moore's 1st Law [Benefits]

per second

\$1000 Buys: Computations



Scaling: The Benefits and the Costs -Ex. Moore's 1st Law [Benefits]



~\$9,000,000

80 GB Storage

<\$140

The Impact of Scaled Nanotechnology

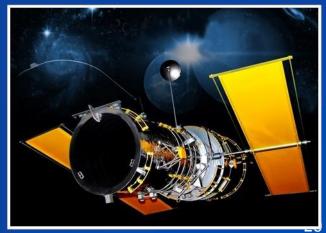
Scaling has allowed product and systems manufacturers to dramatically increase performance, while dropping costs in:

- Computers & information systems
- TVs, radios & audio systems
- Defense/Aerospace electronics









University research often fuels options, but rarely predicts, market success.

Precise Control of Atoms in Semiconductor Materials (Stanford)

Single Crystals of SiC and GaN (NCSU)

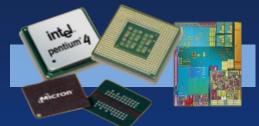
Laser Crystallization of Amorphous Silicon (Cornell, MIT, CalTech, Columbia)

Hot-electron Injection in Thin Films of Insulators (Berkeley)

~ 20 Years Later



Microchips with > 1 Billion Transistors





Cell-phone
Displays,
Traffic Lights,
LEDs





Flat Panel Displays





Digital Cameras, Memory Sticks, iPod



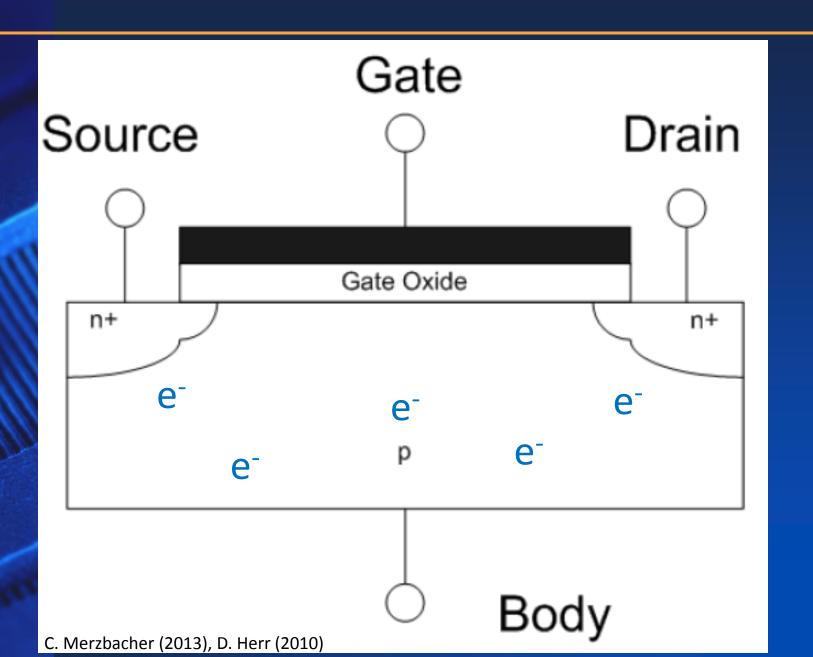
Scaling: The Benefits and the Costs-Ex. Moore's 1st [Benefits] and 2nd Laws [Cost] J. E. Kelly III - IBM adapted from Kurzweil 1999 and Moravec 1998; D. Herr, SRC 2011 second 1970 Fab Cost 1E+12 Nano-IC Over the past 35 ~\$10 M per years, prices for **Integrated Circuit** 1E+9 almost everything Computations have increased by **Discrete Transistor** 1E+6 2011 Fab Cost 5 - 10 fold. ~\$11 B Vacuum Tube 1E+3 **Semiconductor** 1E+0 **Electro-mechanical** \$1000 Buys: unit prices have Mechanical 1E-3 decreased by a factor of a million. 1E-5 1980 1900 1920 1940 2000 2020 1960 iPOD (5G) > 25,000 X cost 126 IBM 3350's @ **3TB Today** 635MB/Machine in 1976 [80GB~\$3.73] 80GB in 2006 reduction

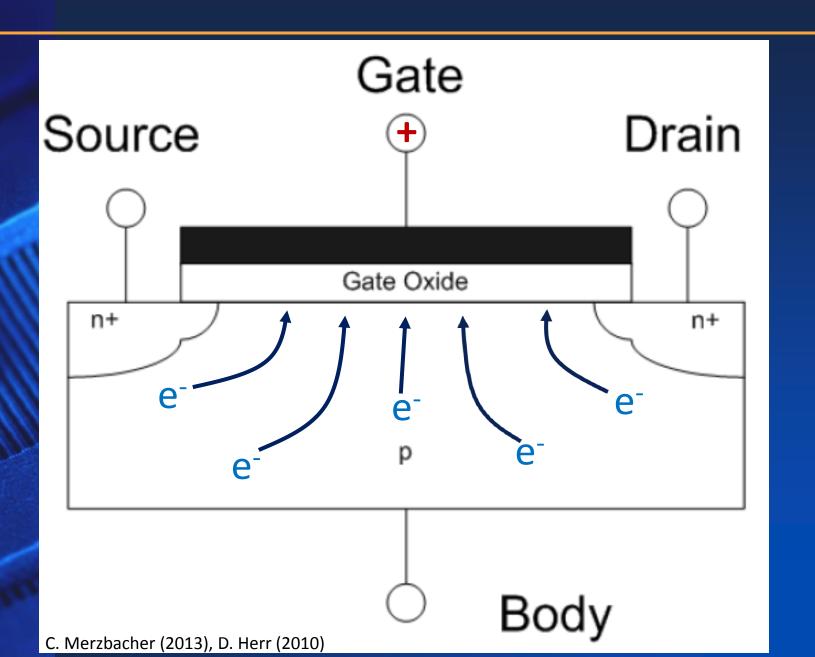
~\$9,000,000

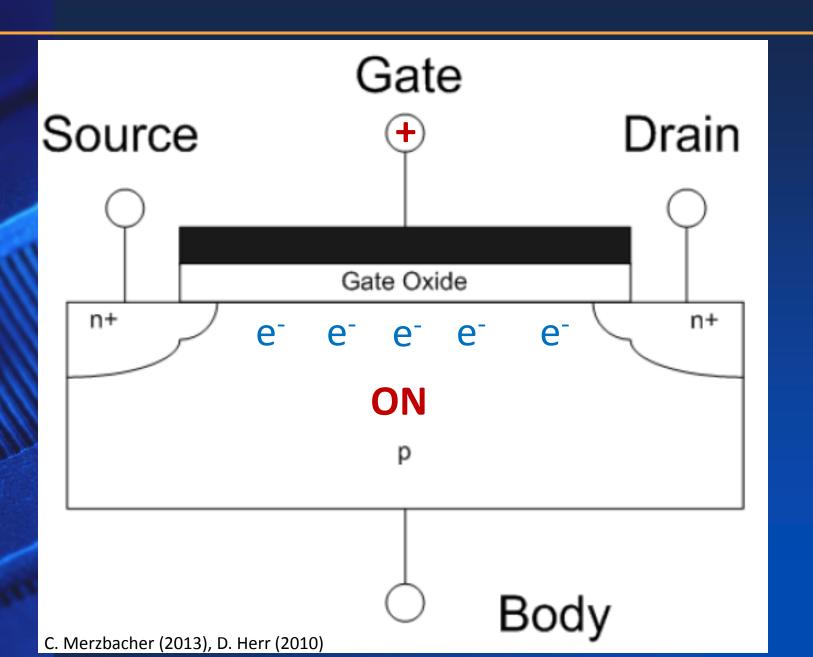
80 GB Storage

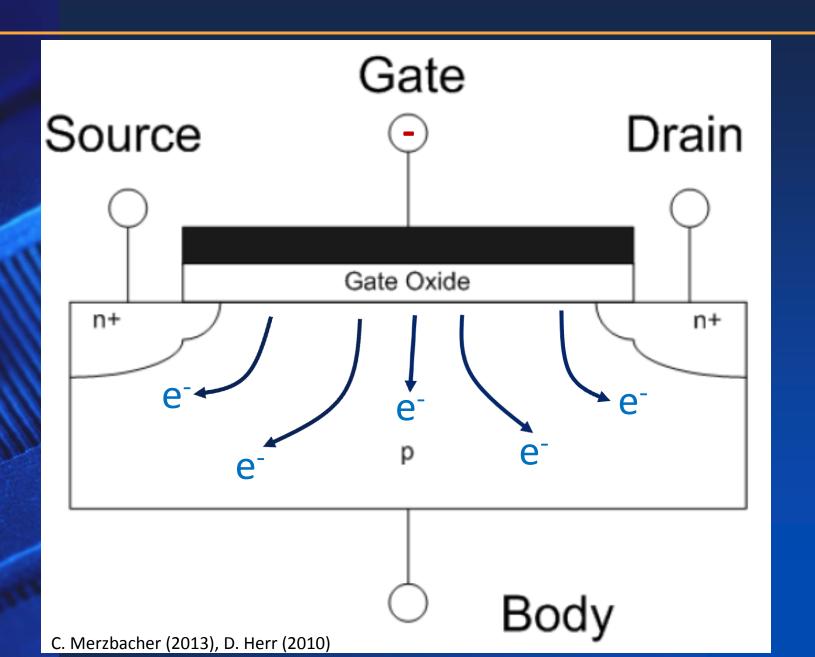
\$349

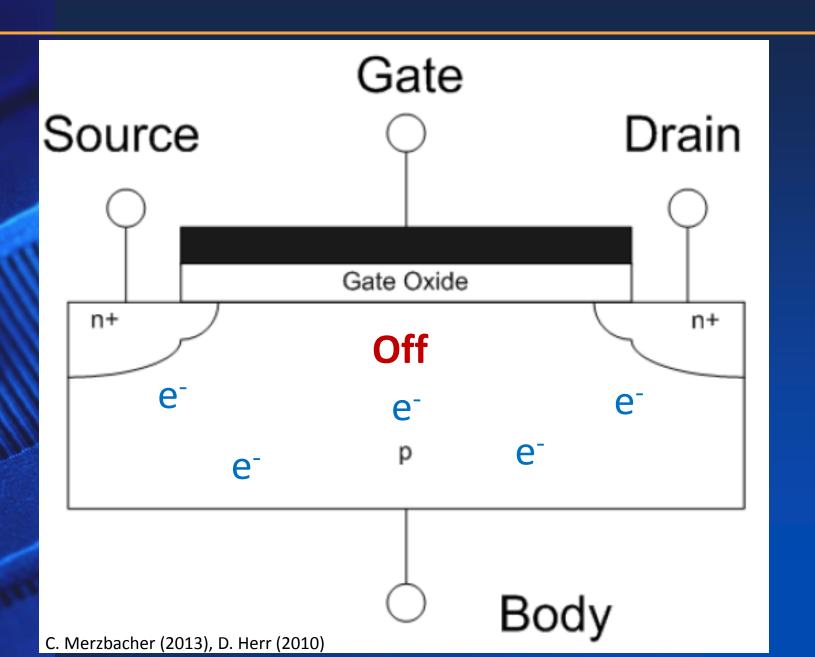
<\$140









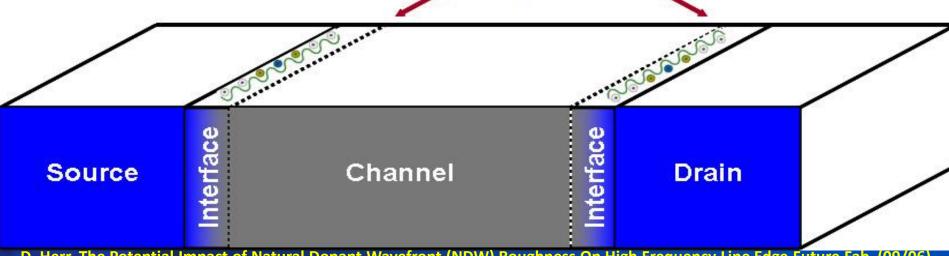


Fully Depleted Device Challenges:

Channel and interface variability

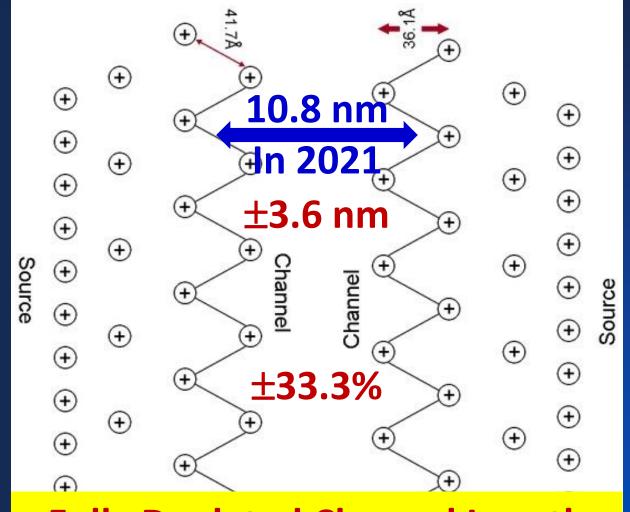


Natural Dopant Wavefront



Top down fabrication wall:

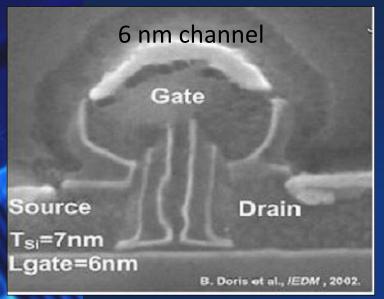
Ex. Channel interface variability



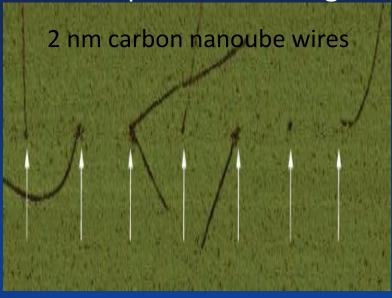
Fully Depleted Channel Length Variation ~ 66.6 % by 2021

Ultimate Semiconductor Device Components?

CMOS switch



Nanoscopic and atomic gold



Dai et al.

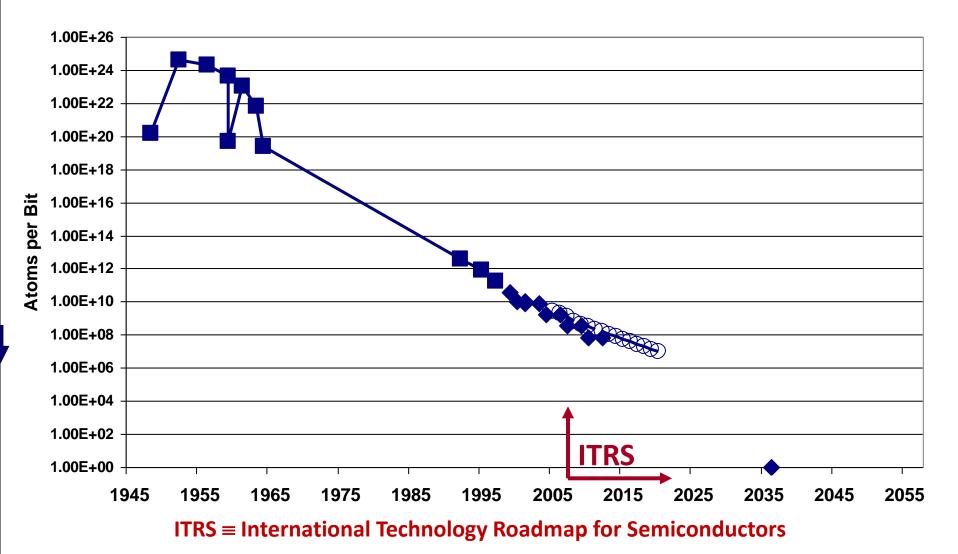
Doris et al. (2002)

Single Atom Transistor

B Ejected Si O Arthur O Arthur

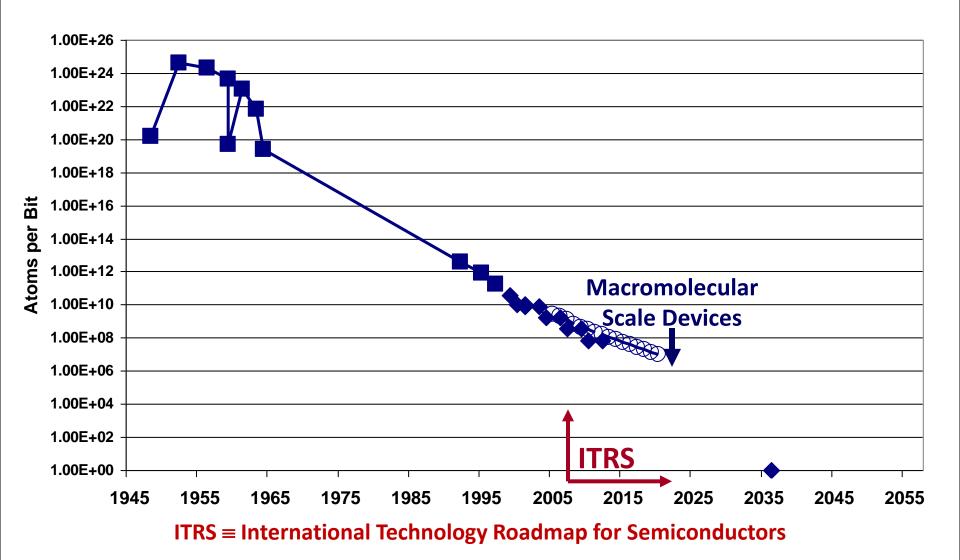
M. Simmons et al. 2012

Towards Macromolecular Scale Devices: The trend in atoms per bit and material complexity



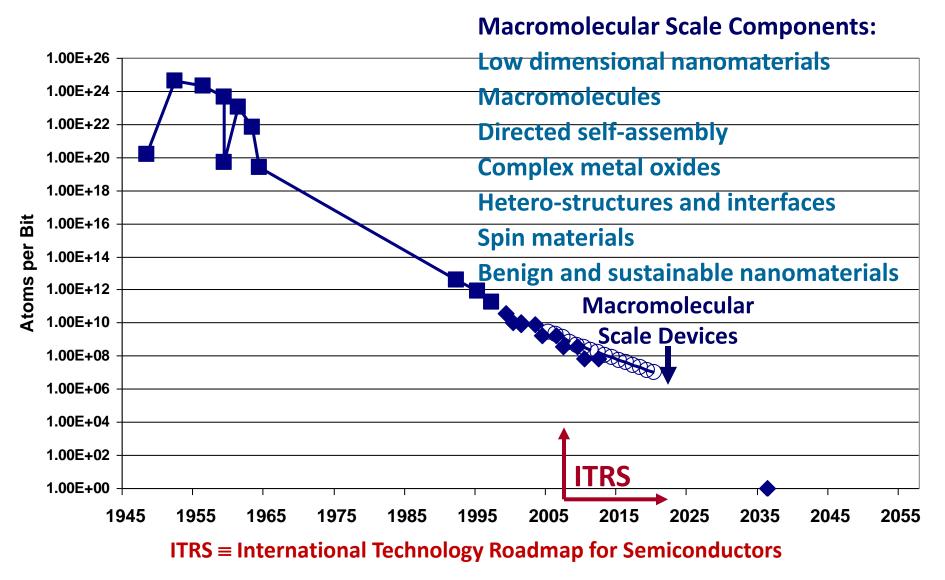
Revised 2006 from: D. Herr and V. Zhirnov, Computer, IEEE, pp. 34-43 (2001).

Towards Macromolecular Scale Devices: The trend in atoms per bit and material complexity



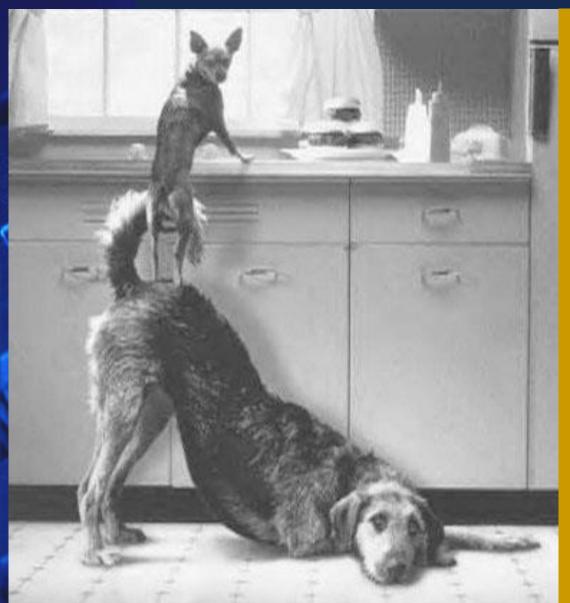
Revised 2006 from: D. Herr and V. Zhirnov, Computer, IEEE, pp. 34-43 (2001).

Towards Macromolecular Scale Devices: The trend in atoms per bit and material complexity



Revised 2006 from: D. Herr and V. Zhirnov, Computer, IEEE, pp. 34-43 (2001).

Beyond Scaling: Pursuing the race for added value for the end customer by combining on-chip ULSI and off-chip integration

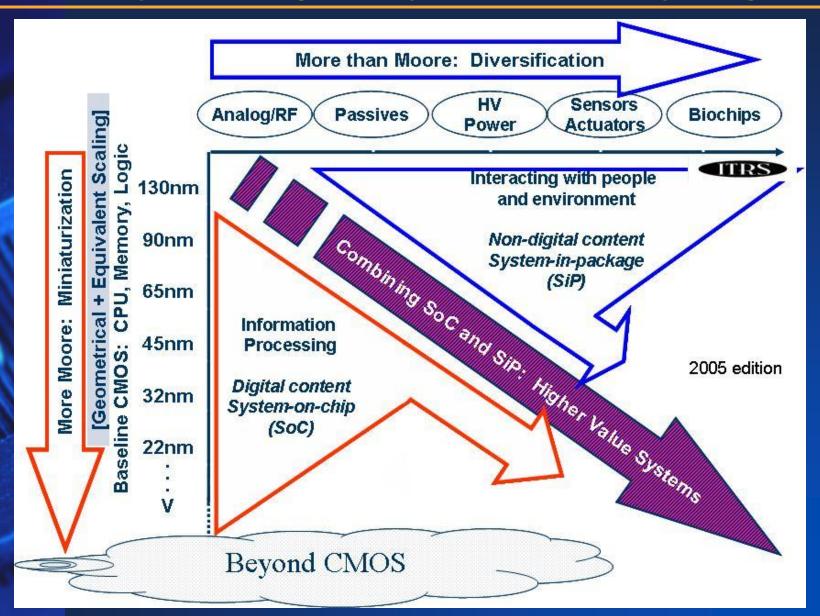


Perhaps one technology cannot do it all alone.

There may be synergistic computational benefits from leveraging the collective action of several functional elements.

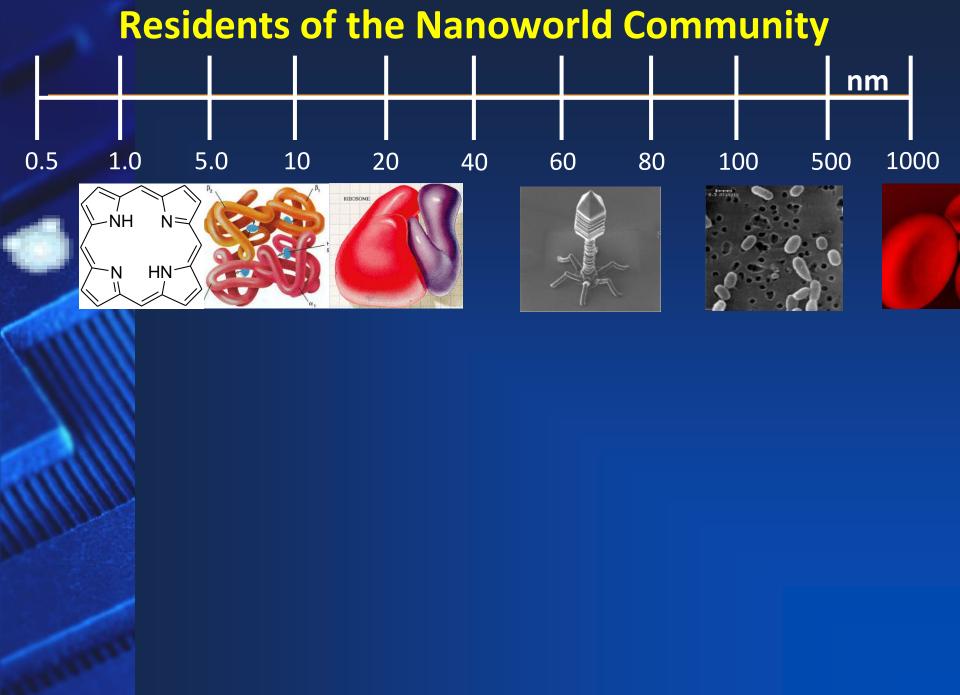
A key challenge is to develop nanoscale fabrication methods for enabling heterogeneous integration on CMOS.

Beyond Scaling: Pursuing the race for added value for the end customer by combining on-chip ULSI and off-chip integration

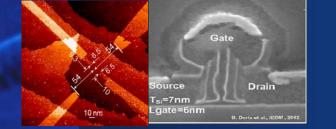


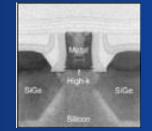
Invention and Innovation are Needed

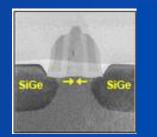
Beyond ~ 2020, a <u>completely different approach</u> to information processing will be needed.



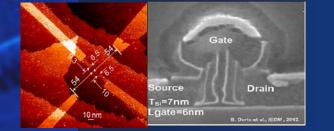
Residents of the Nanoworld Community nm 0.5 1000 1.0 5.0 10 20 40 60 80 500 100 HN

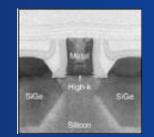


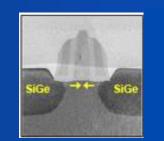


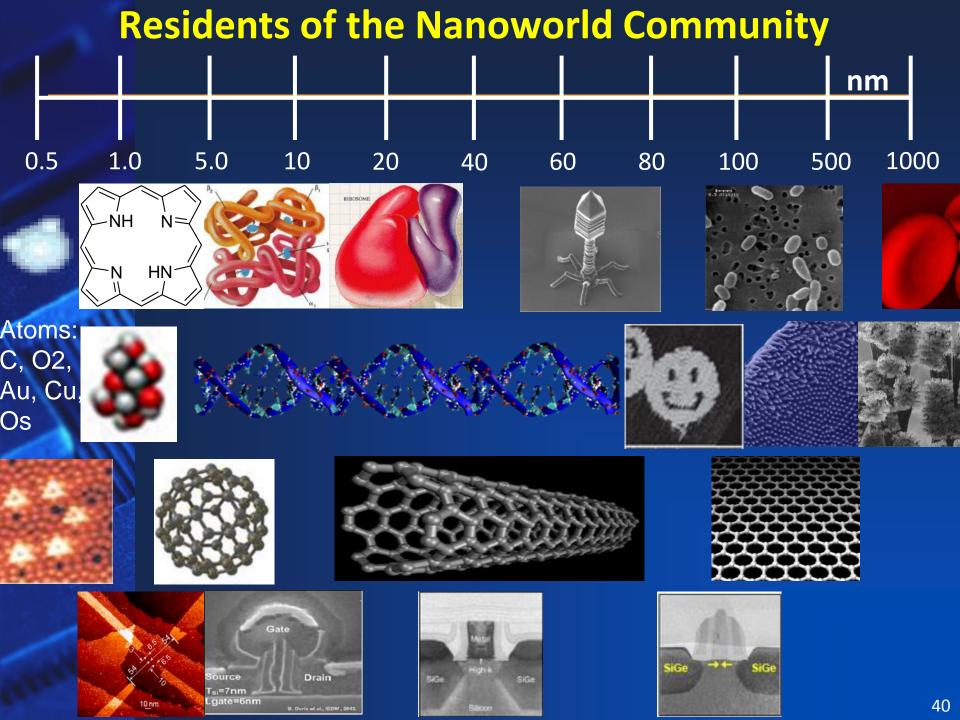


Residents of the Nanoworld Community nm 0.5 1000 1.0 5.0 10 20 40 60 80 500 100 HN Atoms: C, O2, Au, Cu Os









Invention and Innovation are Needed

Beyond ~ 2020, a <u>completely different approach</u> to information processing will be needed.

We are likely to see a revolution in convergent technologies comparable to the monolithic integration of transistors more than fifty years ago.



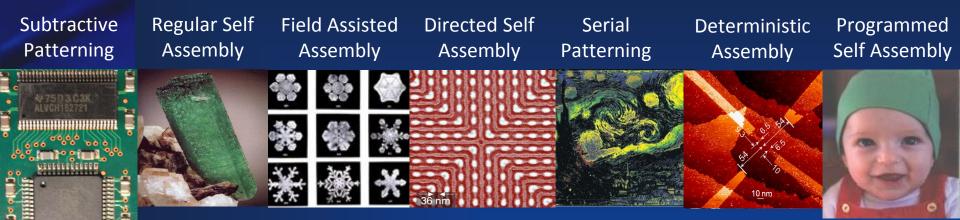
Question Break



Deterministic Programmed Assembly Self Assembly



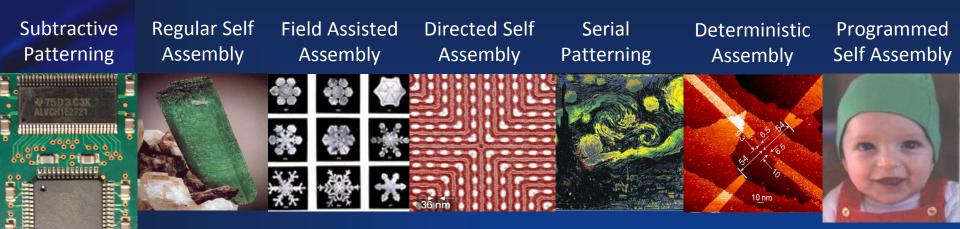




Nature offers a hierarchy of fabrication options.





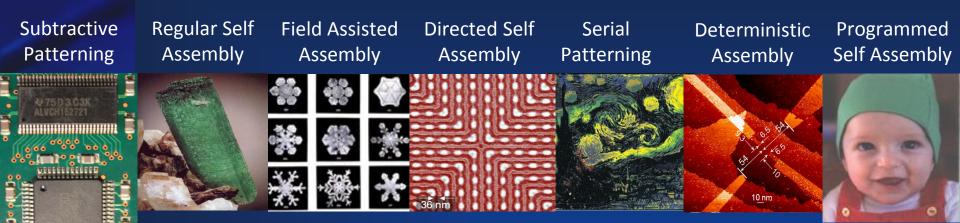


Increasing material information content

Nature offers a hierarchy of fabrication options.







Increasing material information content

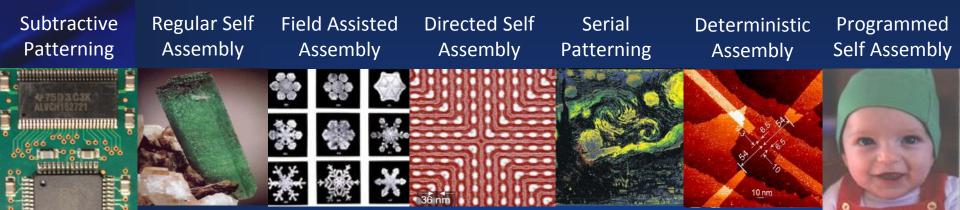
Nature offers a hierarchy of fabrication options.



Semiconductor

Manufacturing





Semiconductor

Increasing material information content

of fabrication options.

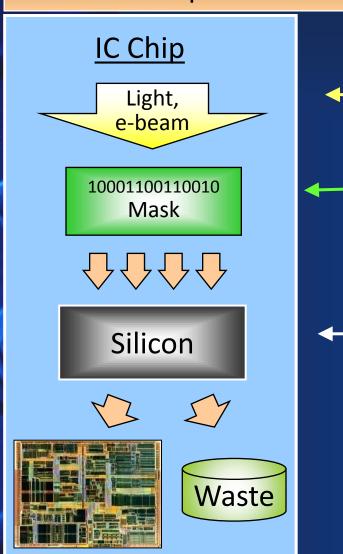


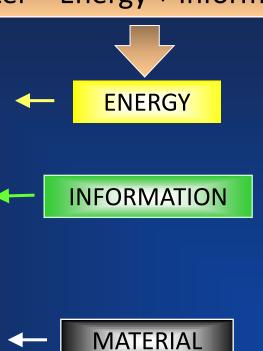




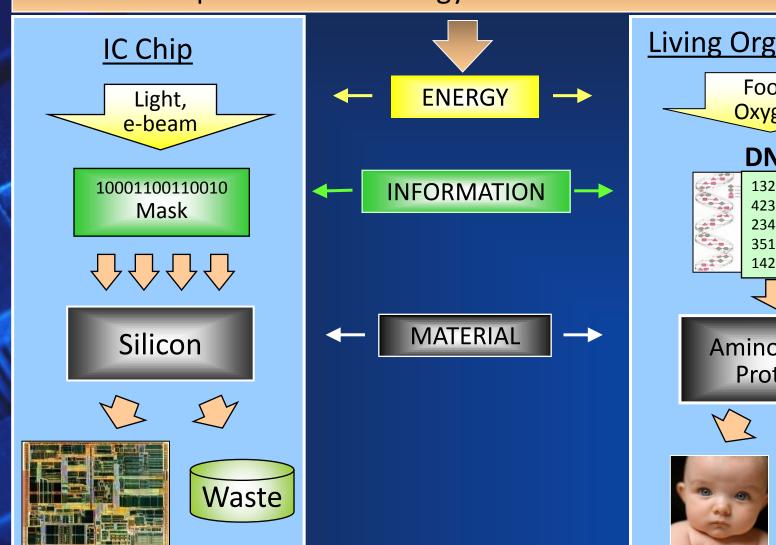


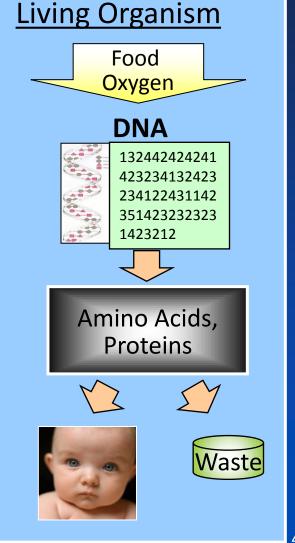
Subtractive Versus Assisted/Additive Assembly



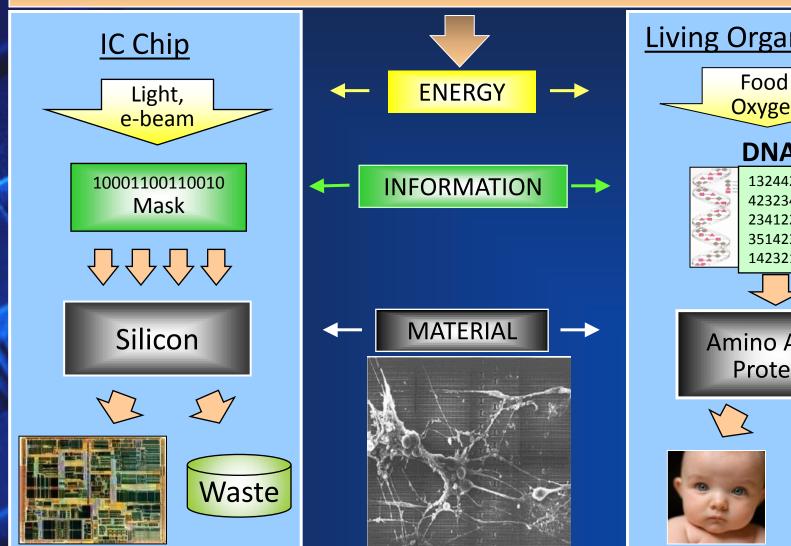


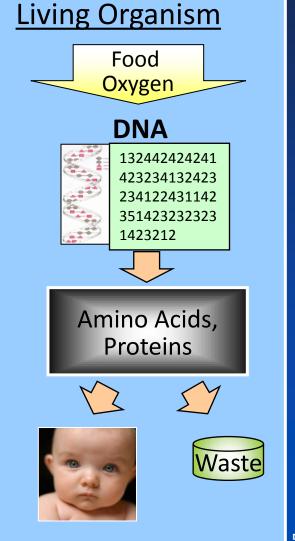
Subtractive Versus Assisted/Additive Assembly

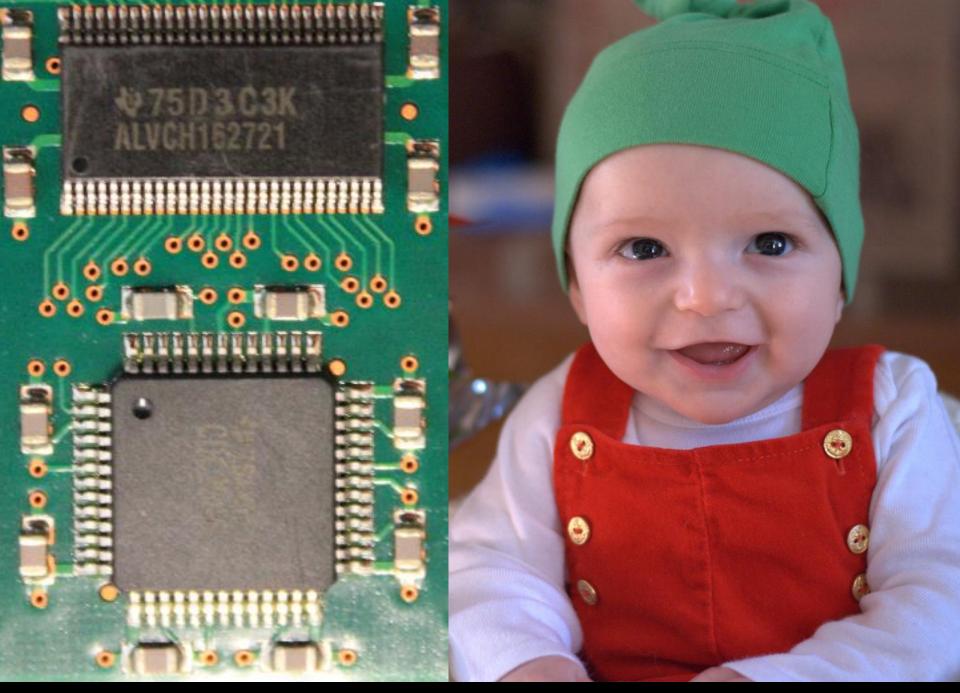




Subtractive Versus Assisted/Additive Assembly







Top-down vs bottoms-up fabrication:

Ex. Comparing computer chips and babies

	Fab output	Baby growth	Nature's advantage
Rate	< 1.3E+9 bits/s	> 1.5E+17 amino acid/s	>1E+8

Top-down vs bottoms-up fabrication:

Ex. Comparing computer chips and babies

	Fab output	Baby growth	Nature's advantage
Rate	< 1.3E+9 bits/s	> 1.5E+17 amino acid/s	>1E+8
Energy	>>2.1E-8 J/bit	<6.6E-17 J/amino acid	>3E+8

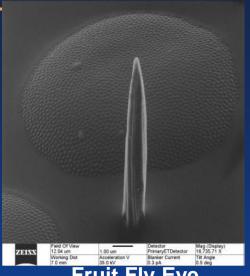
JSNN's Interdisciplinary Research Platforms



C G T T Date: for View Son 00 err Permany Tolerctor A T R Angle N T R Angle N

DNA Structure
J. Yang, Carl Zeiss

- Nanomaterials
- Nanobiology
- Nanobioelectronics
- Nanometrology
- Nanoenergy
- Computational Nanotechnology



Fruit Fly Eye,
D. LaJeunesse, JSNN





What can we learn from Nature? Ex. Alternative assembly methods

Subtractive Patterning

Regular Self Assembly Field Assisted Assembly

Directed Self
Assembly

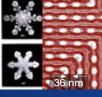
Serial Patterning

Deterministic Assembly Programmed Self Assembly

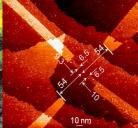












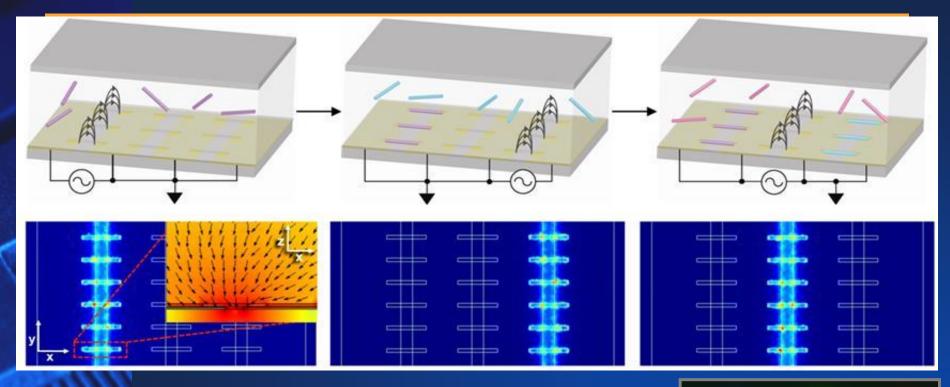








Field and surface assisted assembly



Coupling sequential delivery with a field directed assembly directs different nanowire populations to different regions of the chip and then preferentially aligns individual nanowires within lithographically-defined microwells.

Morrow, Mayer, Keating et al. Science, 323, 352 (2009).

What can we learn from Nature? Ex. Alternative assembly methods

Subtractive Patterning

Regular Self Assembly Field Assisted Assembly

Directed Self Assembly

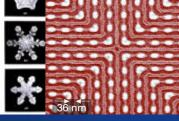
Serial Patterning

Deterministic Assembly Programmed Self Assembly

















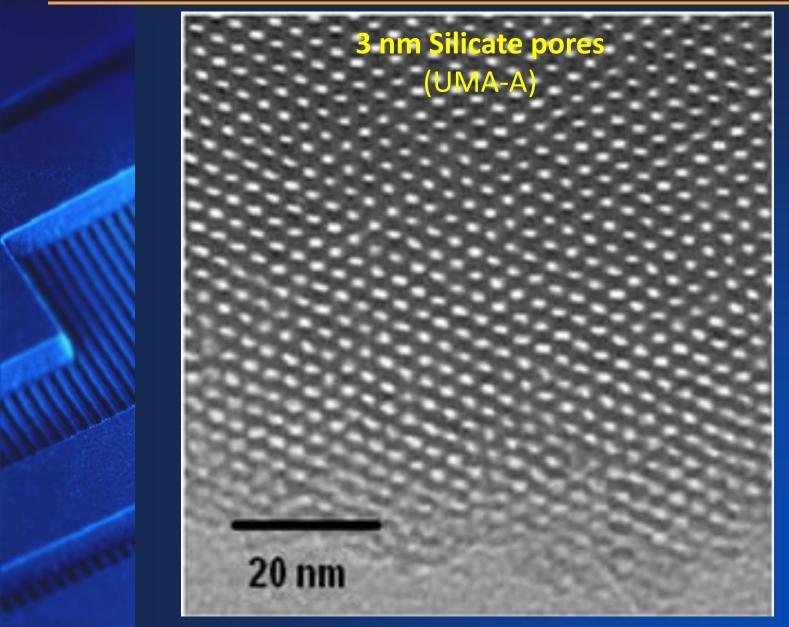




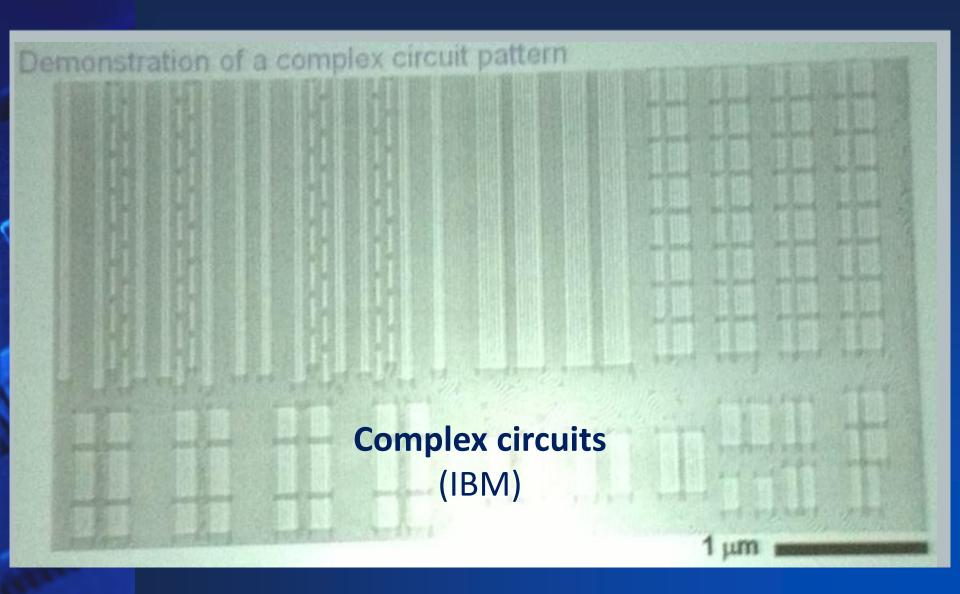
Biomimetic and Directed Self Assembly D. Herr, D. LaJeunesse, and A. Hung



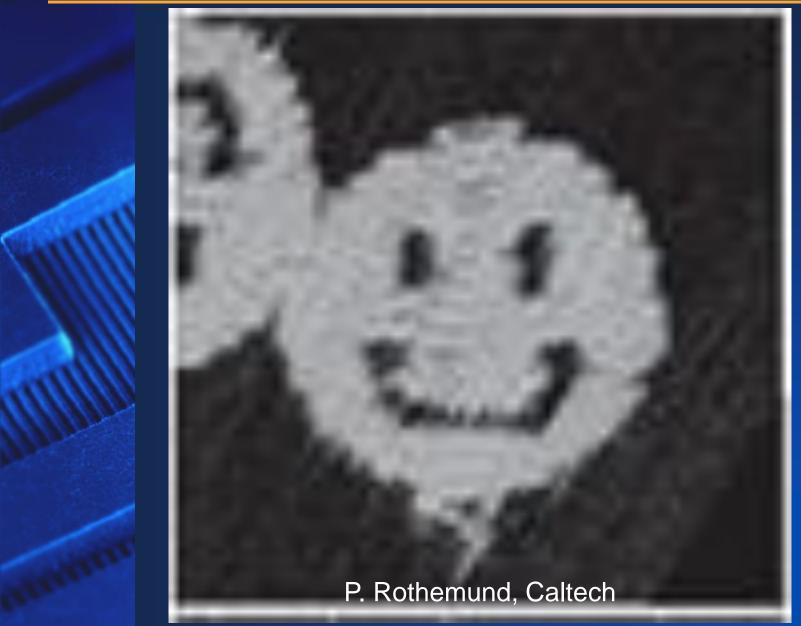
Directed Self AssemblyResolution and complexity



Directed Self AssemblyResolution and complexity

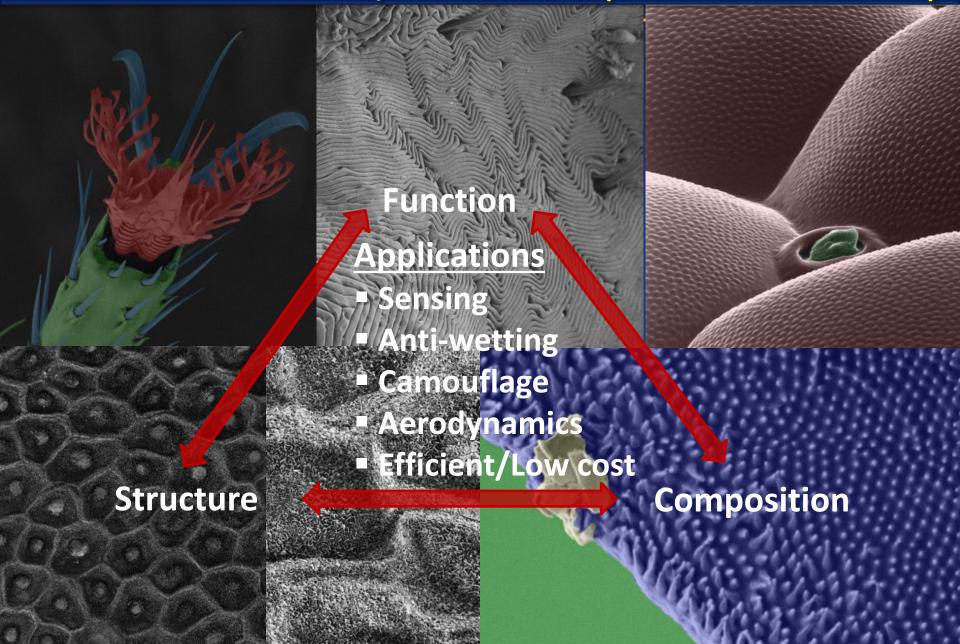


Directed Self AssemblyResolution and complexity

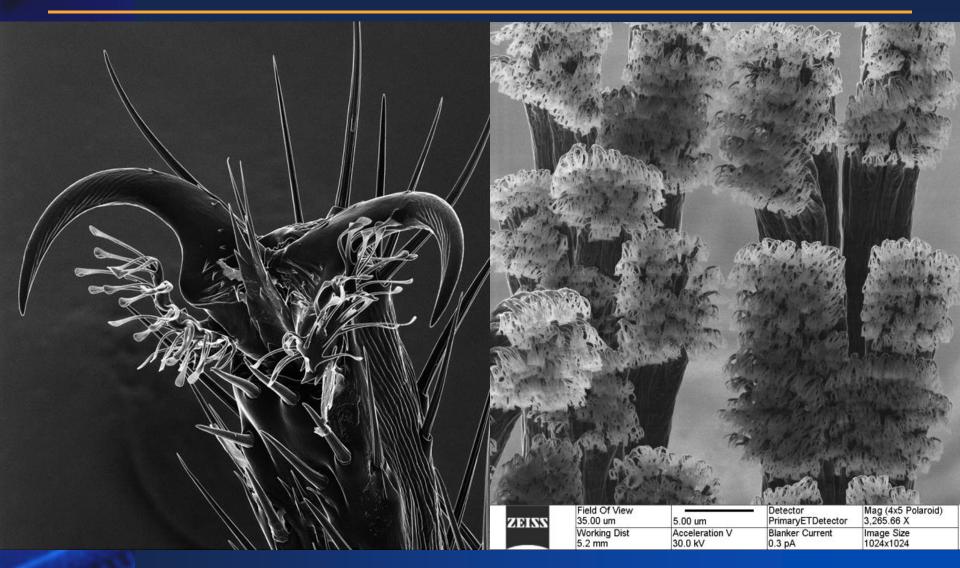


Functional Nanomaterials

Biomimetic Nanomaterials/Nanostructures (D. LaJeunesse & D. Herr)

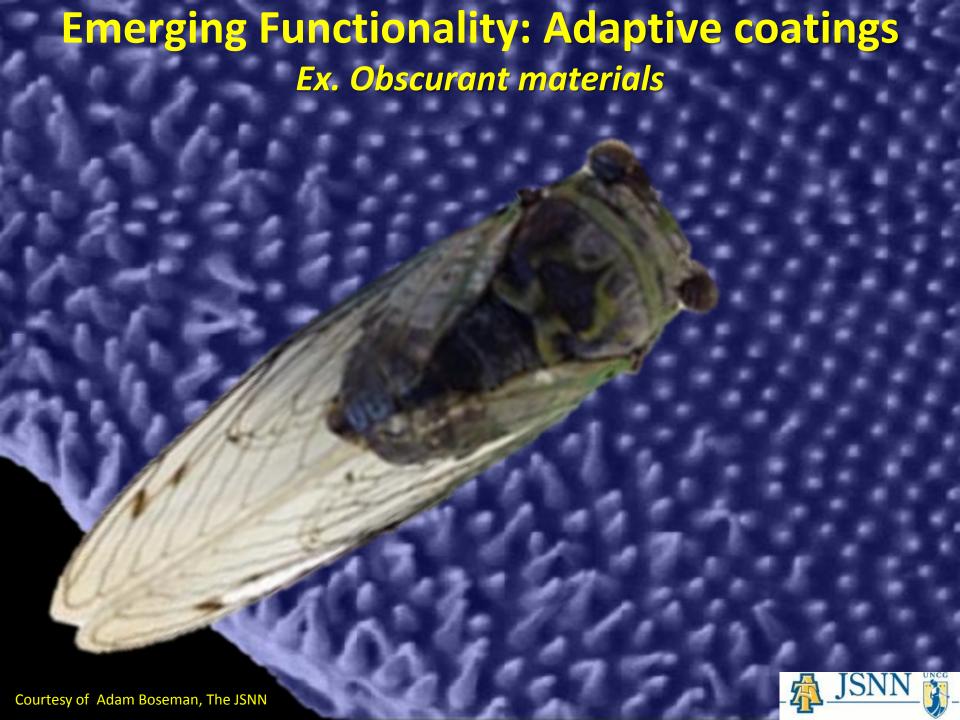


Nature Leverages Functional Nanostructures



Fruit Fly Foot

Gekko Foot

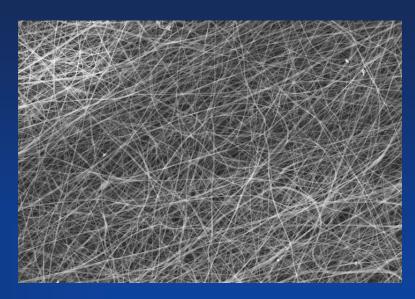


Structural Nanocomposite Materials

Smart/Protective Skin, Fuel Cell Powered, Nano-Composite Vehicles



Spun Nanoglass Fiber Matrix



Structural Nanocomposite Materials

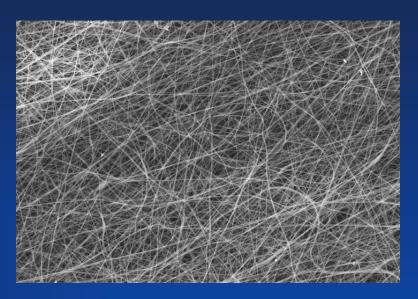
Smart/Protective Skin, Fuel Cell Powered, Nano-Composite Vehicles



Light and Strong Nanocomposite Structures



Spun Nanoglass Fiber Matrix

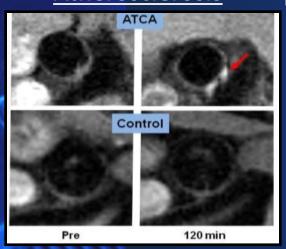


Nanocarbon Laminate



Nanobiology Nanotheranostics (C. Kepley)

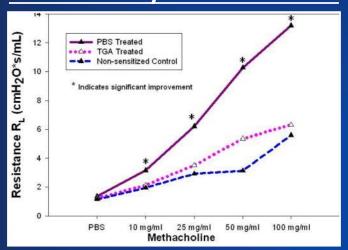
Atherosclerosis



Atherosclerotic-plaque targeting contrast agents (ATCA) can detect plaque in vivo.

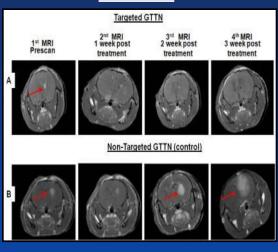
Empty cage C60 Empty cage C70 Metallo-fullerene

Inflammatory disease-asthma



Fullerenes improve asthma symptoms.

Cancer



Glioblastoma targeting theranostics (GTTN) shrink brain tumors.





Nanobioelectronics

Integrated Nerve Stimulation Device (J. Starobin and S. Aravamudhan)

3D high-density peripheral nerveelectrode interface in order to re-establish nerve conductivity

(Regenerative Microchannelbased Electrode Interface - ReME)

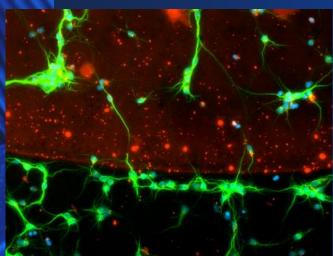
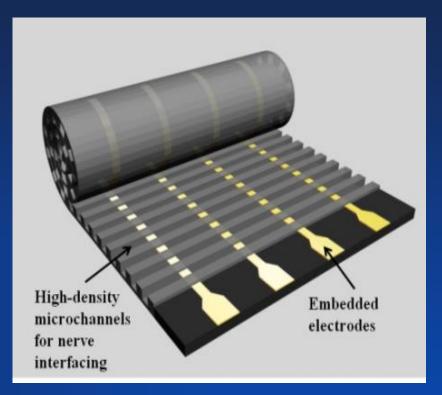


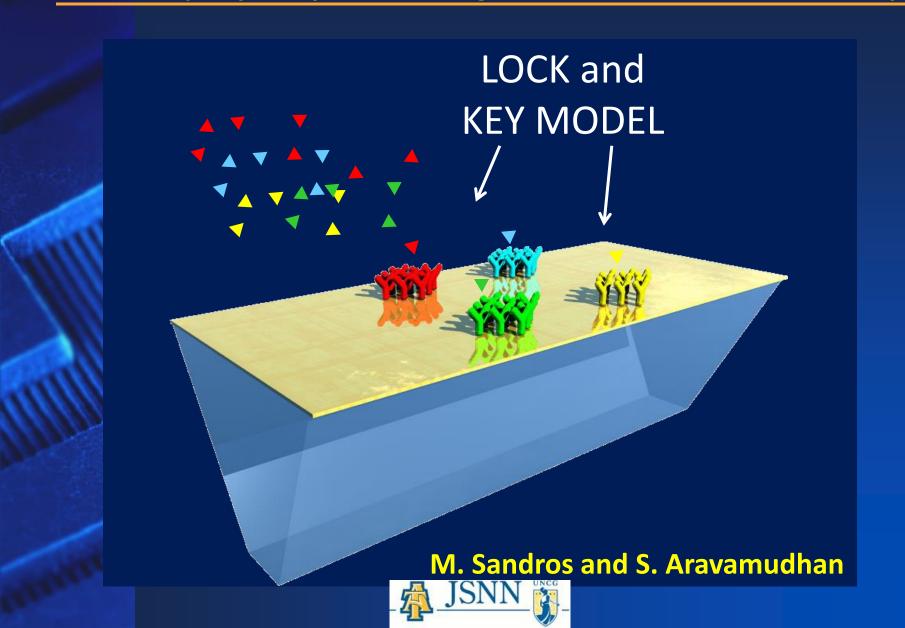
Image of stained neuronal cells on electrodes



3D micro-channel array embedded with electrodes for stimulation of nerve fibers

Emerging Functionality: Bioelectronics

Ex. Portable platform for detecting moderate traumatic brain injury



Bioinspired Functionality: Convergent Integration Opportunities

Typical Functionality Integrated Within a Cell

Energy	Generation Conversion Storage Utilization Architectures	Communication	Transmission Filtering Novel A/D Interconversions Low Energy Approaches Reception
Sensing	Physical Chemical Multimode Multiscale Subsurface	Bioelectronics	Personalized Medical Diagnostics Prosthetics and Implantable Devices Biotic/Abiotic Interfaces Multiproperty Imaging Noninvasive [Tricorder-like]
Actuation	Analog Digital Hybrid Approaches Hard and Soft/Adaptive Systems Autonomous Emergent Behavior	Adaptive Coatings	Dynamic Local Mapping Camouflage Obscuration Smart Physical Changes Remotely Directed Adaptations

D. Herr, SRC SemiSynBio Workshop, February 2013

Bioinspired Functionality: Convergent Integration Opportunities

Typical Functionality Integrated Within a Cell

Energy	Generation Conversion Storage Utilization Architectures	Communication	Transmission Filtering Novel A/D Interconversions Low Energy Approaches Reception
Sensing	Physical Chemical Multimode Multiscale Subsurface	Bioelectronics	Personalized Medical Diagnostics Prosthetics and Implantable Devices Biotic/Abiotic Interfaces Multiproperty Imaging Noninvasive [Tricorder-like]
Actuation	Analog Digital Hybrid Approaches Hard and Soft/Adaptive Systems Autonomous Emergent Behavior	Adaptive Coatings	Dynamic Local Mapping Camouflage Obscuration Smart Physical Changes Remotely Directed Adaptations

D. Herr, SRC SemiSynBio Workshop, February 2013

Emerging Opportunities: Convergence between traditional and nano- technologies

Ex. Bioelectronics - Lab-on-a-chip:

Selected lab test market opportunity

~ \$10T per year



Question Break

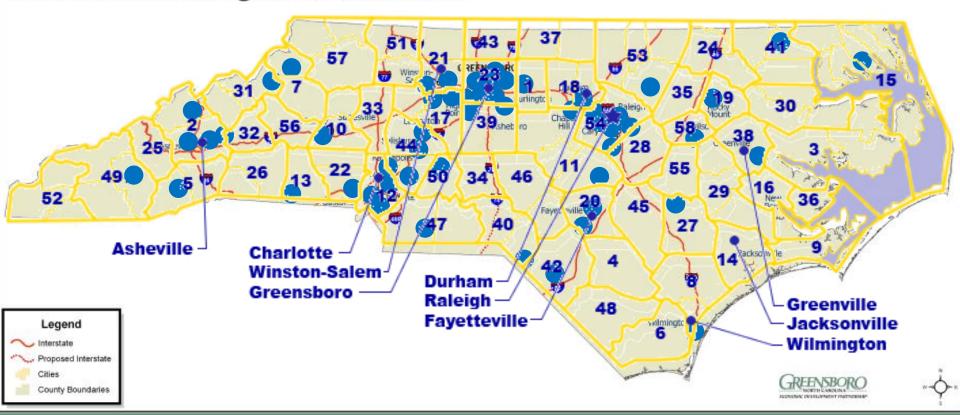
A Story: The Return of U.S. Manufacturing S. Kinkaid

As the Boston Consulting Group reported in May,

"Within the next five years, the United States is expected to experience a manufacturing renaissance as the wage gap with China shrinks and certain U.S. states become some of the cheapest locations for manufacturing in the developed world. We expect net labor costs for manufacturing in China and the U.S. to converge by around 2015. As a result of the changing economics, you're going to see a lot more products 'Made in the USA' in the next five years."

Potential for Innovative Educational Networks

North Carolina Colleges and Universities



We need to nurture a collaborative and well leveraged education, research, and development supply chain

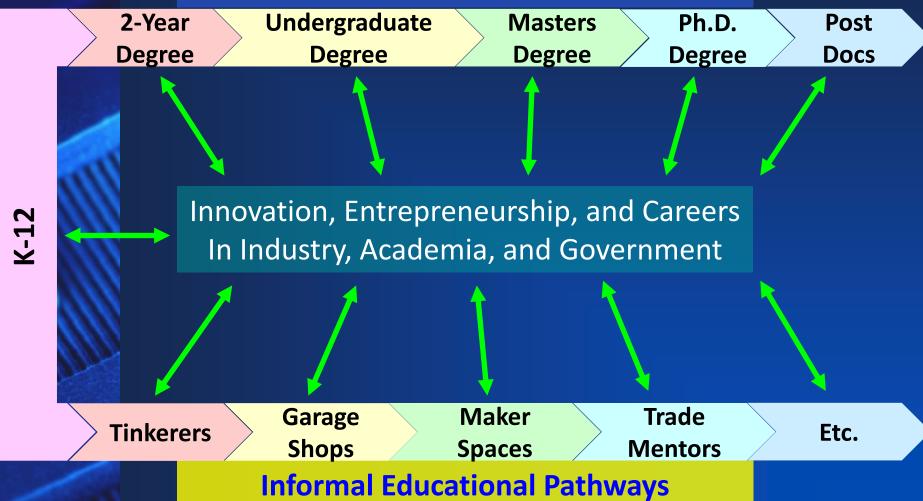


Workforce Education and Training with the qNano



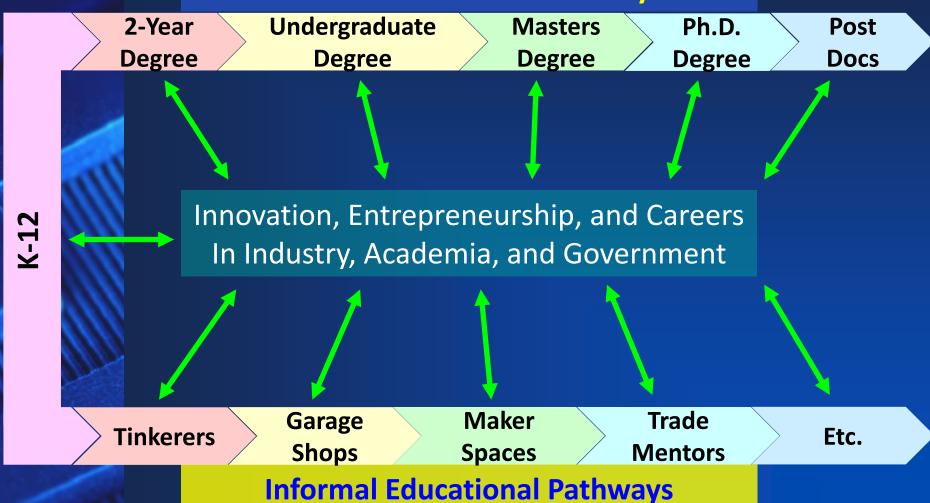
The Dynamic Innovation Infrastructure: Nanoeducational-Entrepreneurial Pipeline

Formal Educational Pathways



The Dynamic Innovation Infrastructure: Nanoeducational-Entrepreneurial Pipeline





Anyone can innovate, create value, and enhance our workforce.

Invention and Innovation are Needed

Beyond ~ 2020, a <u>completely different approach</u> to information processing will be needed.

We are likely to see a revolution in convergent technologies comparable to the monolithic integration of transistors more than fifty years ago.

The seeds of the next wave of innovation have been planted and nurtured in unexpected places all along the formal and informal educational and entrepreneurial supply chain.

Building Small Stuff

Ex. Some emerging high impact fabrication options



2D ink-jet printing

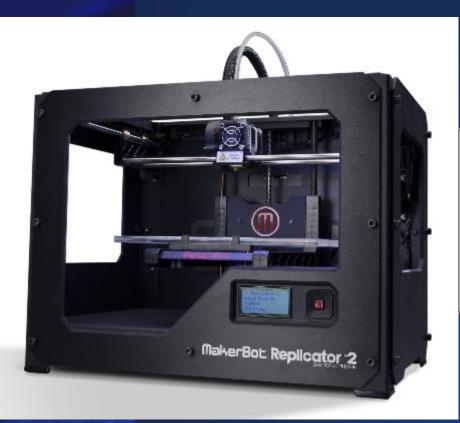
3D Fabrication

Electrospinning

Arrayed dip-pen patterning

3D Fabrication:

Ex. MakerBot



MakerBot Replicator 2 Desktop 3D Printer

By MakerBot Industries
3.6 out of 5 stars See all reviews (7 customer reviews)

Price: \$2,199.00 & FREE Shipping. Details

Only 10 left in stock.

Sold by MakerBot and Fulfilled by Amazon.

The 3D Fabrication: Child's play? Ex. Falling Water: Lego and 3D printed version

These systems could use functional electronic materials.



http://www.robertsoninnovation.com/another-cool-way-to-generate-a-3d-model-minecraft/

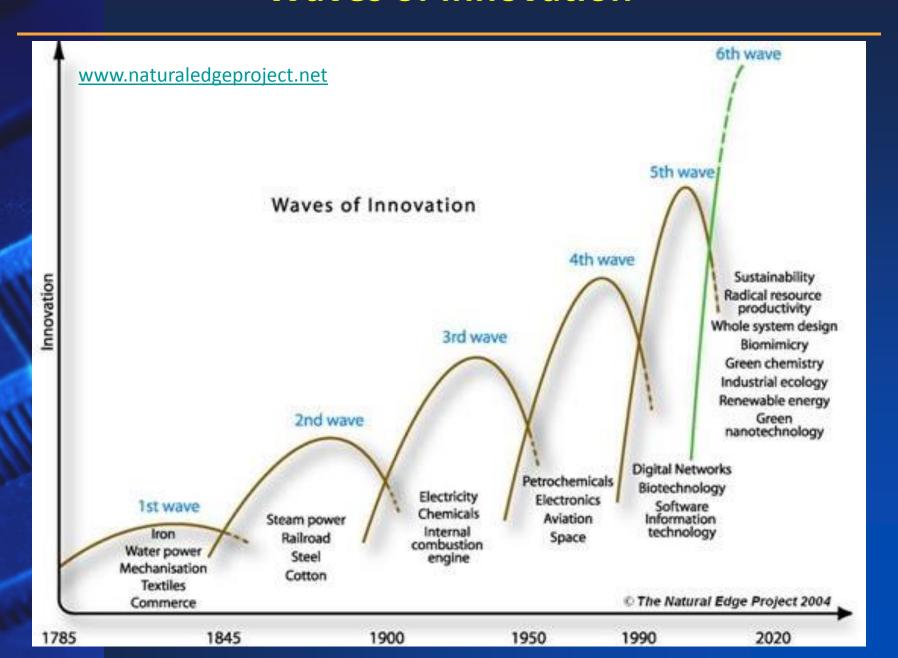
Replace colors with functional materials.

The 3D Fabrication: High impact Ex. Robohand



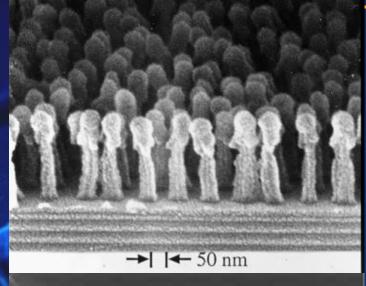
http://www.youtube.com/watch?v=A6isKsPWubA

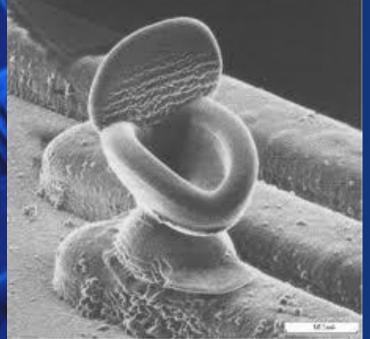
Waves of Innovation

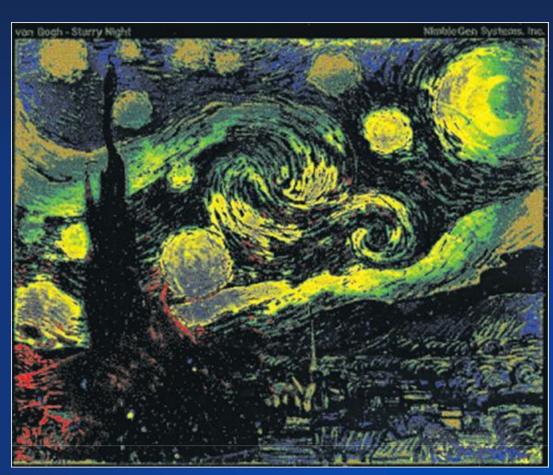


Nontraditioanl Convergent Opportunities:

Nanoart







An activated gene chip F. Cerrina(UW-M)

Key Messages

- ☐ Today's nanomaterials and tools provide unprecedented opportunities for today's students, scientists, engineers, innovators and entrepreneurs to support each other and create high value products that address emerging societal needs.
- This is a good time for innovators to question some of our basic assumptions about designing and building value added products in the micro- and nano- domains.
- □ It is imperative that educators keep current with these rapidly evolving technologies to ensure that workforce entrants have the knowledge, skills and abilities they will need.

Have we reached the tipping point?

I welcome your thoughts and hearing about the challenges that are capturing our children's imagination.

How small can we go?



How small can we go?

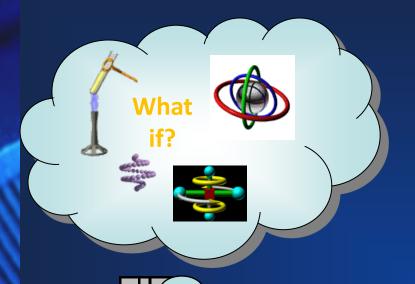
Ultra-micro-bacteria (~200 nm)



Extracted from a glacial ice core sample, 120,000 years old Miteva (2005)

How small can we go?

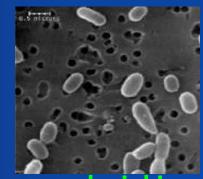




Thank You

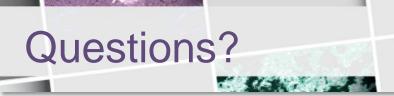


Ultra-micro-bacteria (~200 nm)



djherr@uncg.edu

Extracted from a glacial ice core sample, 120,000 years old Miteva (2005)





Please type all questions into the Chat Box

How Can We Better Serve You?



Whether you are joining us live or watching the recorded version of this webinar, please take 1 minute to provide your feedback and suggestions.

http://questionpro.com/t/ABkVkZQFNf

Webinar Recordings

To access this recording, slides, and handout visit nano4me.org/webinars.php

Certificate of Participation



If you attended the live version of this

1.5 hour webinar and would like a
certificate of participation, please email:

sbarger@engr.psu.edu

2013 – 2014 Events Calendar

Carlo Land



Nov. 12-14: Hands-on Introduction to Nano for Educators

Workshop

January 31: K-12 Resources in Nanotechnology

Webinar

March 28: RET Experience: Activities for the HS

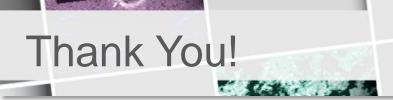
Webinar Classroom

April 7-10: Nanotechnology Course Resources

Workshop Workshop 1: Safety, Processing, and

Materials

Want more events? Visit www.nano4me.org/webinars for more details about these and other upcoming workshops and webinars in 2014.



Thank you for attending the NACK Network webinar

Catching the Nanotechnology Wave: Needs, Risks, and Opportunities